

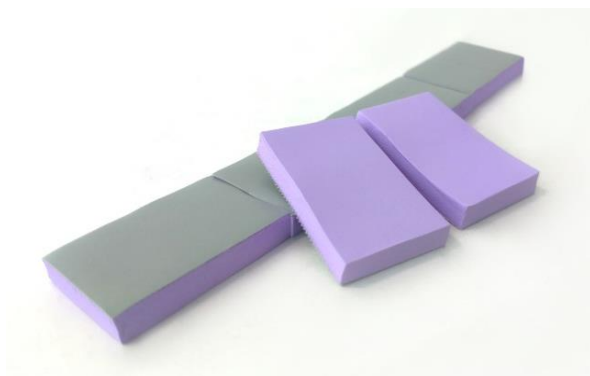
PT-TG-4500F

Ultra Soft Thermal Pad

REACH

RoHS

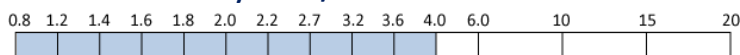
UL



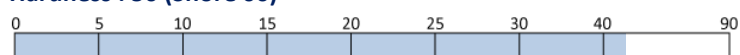
Features

- Very good thermal conductivity
- Fiberglass on one side
- Non deforming
- Electrical insulation

Thermal Conductivity : 4 W / mK



Hardness : 50 (Shore 00)

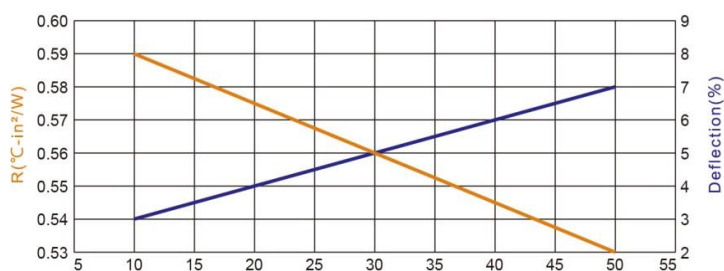


Applications

Best for high power applications

Electronic components: IC, CPU, MOS, LED, Mother Board, Power Supply, Heat Sink, LCD-TV, Notebook, PC, Telecom Device, Wireless Hub, DDR II Module, DVD Applications, Hand-set applications etc.

Thermal Resistance VS. Pressure VS. Deflection



Pressure (psi)	R (°C-in²/W)	Deflection (%)
10	0.59	3
30	0.56	5
50	0.53	7

Properties

Properties	PT-TG-4500F	Unit	Tolerance	Test Method
Thermal Conductivity	4	W / mK	±10%	ASTM D5470
Thickness	0.5~8.0	mm	-	ASTM D374
	0.0197~0.315	inch	-	ASTM D374
Color	purple	-	-	Visual
Reinforcement Carrier	Fiberglass mesh	-	-	-
Flame Rating	V-0	-	-	UL 94
Dielectric Breakdown Voltage	> 6	KV / mm	-	ASTM D149
Weight Loss	<1	%	-	ASTM E595
Density	3.1	g / cm ³	-	ASTM D792
Working Temperature	-50 ~ +150	°C	-	-
Volume Resistance	1 x 10 ¹³	Ohm-m	-	ASTM D257
Elongation	50	%	-	ASTM D412
Standard Shape	Sheet ones	-	-	-
Hardness(Silicone Side)	50	Shore 00	±15	ASTM D2240
Need samples?	Pre-cut for different shapes			

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